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APPROVAL SHEET

MULTILAYER CERAMIC CAPACITORS

Low Profile Series

0402 to 1210 Sizes

X7R, X5R & Y5V Dielectrics

Halogen Free & RoHS Compliance



*Contents in this sheet are subject to change without prior notice.

1. DESCRIPTION

MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used.

WTC TT series MLCC is used in product having thickness concerned generally have high capacitance and thinner product thickness. The high dielectric constant material X7R, X5R and Y5V are used for this series product.

2. FEATURES

- a. Standard size with thin thickness.
- b. Small size with high capacitance.
- c. Capacitor with lead-free termination (pure Tin).

3. APPLICATIONS

- a. For LCD panels.
- b. For PCMCA cards.
- c. For IC packaging and modules.
- d. Any thickness concerned products.

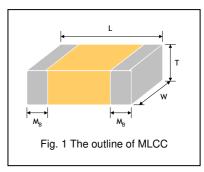
4. HOW TO ORDER

<u>TT</u>	<u>15</u>	<u>X</u>	<u>475</u>	<u>M</u>	<u>6R3</u>	<u>C</u>	Ī
<u>Series</u>	<u>Size</u>	Dielectric	<u>Capacitance</u>	Tolerance	Rated voltage	<u>Termination</u>	<u>Packaging</u>
	45 0400 (4005)	D V7D	L NE LL K	4400	To a little and	O . O /N!: /O	T 7" l l
TT=Low profile	15 =0402 (1005)	B =X7R	Two significant	K =±10%	Two significant	C =Cu/Ni/Sn	T=7" reeled
	18 =0603 (1608)	X =X5R/	digits followed by	M=±20%	digits followed by		G=13" reeled
	21 =0805 (2012)	F=Y5V	no. of zeros. And	Z =-20/+80%	no. of zeros. And		
	31 =1206 (3216)		R is in place of		R is in place of		
	32 =1210 (3225)		decimal point.	5A	decimal point.		
		0	PASSIVE SYS	TEM ALLIANCE	cpe covpo		
		181	eg.:		6R3 =6.3 VDC		
		100	$475=47\times10^5$		100 =10 VDC		
		COPVRIGH	=4,700,000pF		160 =16 VDC		
		C	=4.7µF	10.	250 =25 VDC		
			A/co Chno	CO/Z	500 =50 VDC		
			JEQUE .	UBY TON	101 =100 VDC		



5. EXTERNAL DIMENSIONS

Size Inch (mm)	L (mm)	W (mm)	T (mm)/Symbol		M _B (mm)
0402 (1005)	1.00±0.2	0.5±0.2	0.30±0.03	L	0.25±0.10
0603 (1608)	1.6+0.15/-0.10	0.8+0.15/-0.10	0.50±0.10	Н	0.40±0.15
0805 (2012)	2.00±0.20	1.25±0.20	0.85±0.10	Т	0.50±0.20
1000 (0010)	2 20 1 2 20	1 0010 00	0.85±0.10	Т	0.0010.00
1206 (3216)	3.20±0.20	1.60±0.20	1.15±0.15	J	0.60±0.20
1010 (0005)	3.20±0.30	2.5010.20	0.85±0.10	Т	0.75+0.05
1210 (3225)	3.∠∪±0.30	2.50±0.20	2.00±0.20	K	0.75±0.25



6. GENERAL ELECTRICAL DATA

Dielectric	X7R	X5R	Y5V					
Size		0402, 0603, 0805, 1206, 1210						
Capacitance range*	1μF to 10μF	1μF to 10μF						
Capacitance tolerance**	K (±10%	Z (-20/+80%)						
Rated voltage (WVDC)	10V, 16V, 25V, 50V, 100V	6.3V, 10V, 16V, 25V	10V, 16V, 25V, 50V					
Operating temperature	-55 to +125℃	-55 to +85℃	-25 to +85℃					
Capacitance characteristic		+30/-80%						
Termination		Ni/Sn (lead-free termination)						

^{*} Measured at 1.0 ± 0.2 Vrms, 1.0kHz $\pm10\%$, $30\sim70\%$ related humidity, 25% ambient temperature for X7R, X5R and at 20% for Y5V.

^{*} Reflow soldering process only is recommended.

^{**} Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in a mbient condition for 24±2 hours before measurement.

Multilayer Ceramic Capacitors

7. CAPACITANCE RANGE

7-1 X7R dielectric

	Dielectric						X7R					
	Size	0805			12	206 1210						
Rate	ed voltage (VDC)	10	16	25	50	10	16	25	50	10	16	100
	1.0µF (105)							T				
a)	1.5µF (155)											
Capacitance	2.2µF (225)		Т	T					T			K
ita	3.3µF (335)											
ac	4.7μF (475)	T						Т				
ğ	6.8µF (685)											
	10μF (106)					Т						
	22μF (226)											

7-2 X5R dielectric

	Dielectric									K5R								
	Size		0402 0603 0805 1206					1210										
Rate	ed voltage (VDC)	6.3	10	25	10	16	6.3	10	16	25	6.3	10	16	25	50	10	16	25
	0.22uF (224)			L	Н	Н												
	0.47uF (474)	L		L														
	1.0µF (105)	L			Н	Н		Т	Т	Т		Т	Т	Т				
မွ	1.5µF (155)							T	T			Т	Т	Т				
au	2.2µF (225)	L					7 -	HT	T	J		Т	Т	Т	Т			
C:	3.3µF (335)					141	775	3_	7	7		Т	Т	Т		Т		
Capacitance	4.7µF (475)	L			H	K K	T	пT	T	T.		Т	Т	Т		Т		
ပ	6.8µF (685)				IX		坛	权1	万态	- , '5	1							
	10μF (106)				140	V . 4	$\lambda \tau$	T	T	150	ĽÚ,⊲	J/T		Т		Т		Т
	22uF (226)				177177	*	Т	Т		<f' -<="" th=""><th></th><th>31</th><th>Т</th><th></th><th></th><th></th><th>Т</th><th></th></f'>		31	Т				Т	
	47uF (476)				17						T							

7-3 Y5V dielectric

	Dielectric		Y5V								
	Size		0	0805 1206			12	1210			
Rate	ed voltage (VDC)	10	16	25	50	10	16	25	50	10	16
	1.0µF (105)		\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	0) T		(O)	\$2/			
4	1.5µF (155)			4/11	Ch.		0110	3			
ဗ	2.2µF (225)		Т	35/1		OIOEA,	T///	T	Т		
<u> </u>	3.3µF (335)	Т			(ECHAIDIO	OL CORROLL	TIMI.				
Capacitance	4.7μF (475)	Т	Т		- INDIO	JY EUKYUN	T				
Эğ	6.8µF (685)					T					
	10μF (106)	Т				Т				Т	
	22µF (226)										

8. PACKAGING STYLE AND QUANTITY

Size	Thickness May (mm)	/Cymah al	7" reel				
Size	Thickness Max (mm)	/Symbol	Paper tape	Plastic tape			
0402 (1005)	0.33	L	15k	-			
0603 (1608)	0.60	Н	4k	-			
0805 (2012)	0.95	Т	4k	-			
1000 (0010)	0.95	T	4k	-			
1206 (3216)	1.30	J	-	3k			
1010 (2005)	0.95	Т	-	3k			
1210 (3225)	2.00	K	-	1k			

Unit: pieces



Approval Sheet

9. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	Item	Test Condition	Requirements				
1.	Visual and		No remarkable defect. Dimensions to conform to individual specification sheet.				
2.	Mechanical Capacitance Q/ D.F. (Dissipation Factor)	Cap≤10µF, 1.0±0.2Vrms, 1kHz±10% Cap>10µF, 0.5±0.2Vrms, 120Hz±20%** ** Test condition: 0.5±0.2Vrms · 1KHz±10% TT18X≥475(10V) , TT15X series *Before initial measurement (Class II only): To apply de-aging at 150℃ for 1hr then set for 24±2 hrs at room temp .	Y5V: Rated vol. D.F. 50V ≤7% 25V ≤9%				
4.	Dielectric Strength	* To apply voltage: 250% rated voltage. * Duration: 1 to 5 sec. * Charge and discharge current less than 50mA.	* No evidence of damage or flash over during test.				
5.	Insulation Resistance	* To apply rated voltage for max. 120 sec. * Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp.	≥10GΩ or RxC≥100Ω-F whichever is smaller.				
6.	Temperature Coefficient	With no electrical load. T.C. Operating Temp X7R -55~125°C at 25°C X5R -55~85°C at 25°C Y5V -25~85°C at 20°C *Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24± 2 hrs at room temp. O1005 O201 O20	T.C. Capacitance Change X7R Within ±15% X5R Within ±15% Y5V Within +30%/-80%				
7.	Adhesive Strength of Termination	* Pressurizing force : 5N (≤0603) and 10N (>0603) * Test time: 10±1 sec.	No remarkable damage or removal of the terminations.				
8.	Vibration Resistance	* Vibration frequency: 10~55 Hz/min. * Total amplitude: 1.5mm * Test time: 6 hrs. (Two hrs each in three mutually perpendicular directions.) * Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. * Cap./DF(Q) Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp.	* No remarkable damage. * Cap change and Q/D.F.: To meet initial spec.				
9.	Solderability	* Solder temperature: 235±5°C * Dipping time: 2±0.5 sec.	95% min. coverage of all metalized area.				
10.	Bending Test	* The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm per second until the deflection becomes 1 mm and then the pressure shall be maintained for 5±1 sec. * Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. * Measurement to be made after keeping at room temp. for 24±2 hrs.	The remarkable damage.				
11.	Resistance to Soldering Heat	* Solder temperature: 260±5°C * Dipping time: 10±1 sec * Preheating: 120 to 150°C for 1 minute before imme rse the capacitor in a eutectic solder. *Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. *Cap. / DF(Q) / I.R. Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp.	* No remarkable damage. * Cap change: X7R/X5R: within ±7.5% Y5V: within ±20% * Q/D.F., I.R. and dielectric strength: To meet initial requirements. * 25% max. leaching on each edge.				

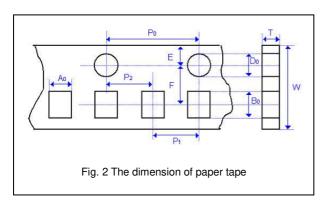
Multilayer Ceramic Capacitors

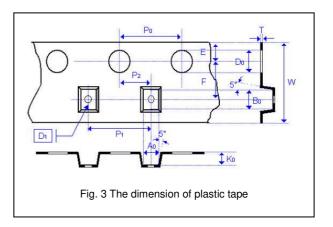


No.	Item	Test Condition	Requirements
12.	Temperature	* Conduct the five cycles according to the temperatures ar	nd * No remarkable damage.
	Cycle	time.	* Cap change :
		Step Temp. (°C) Time (min.)	X7R/X5R: within ±7.5%
		1 Min. operating temp. +0/-3 30±3	Y5V: within ±20%
		2 Room temp. 2~3	* Q/D.F., I.R. and dielectric strength: To meet initial requirements.
		3 Max. operating temp. +3/-0 30±3	
		4 Room temp. 2~3	
		* Before initial measurement (Class II only): To apply de-ag	ging ging
		at 150℃ for 1hr then set for 24±2 hrs at room temp.	
		* Cap. / DF(Q) / I.R. Measurement to be made after de-ag	ing
		at 150℃ for 1hr then set for 24±2 hrs at room temp.	
13.	Humidity	* Test temp.: 40±2℃	*No remarkable damage.
	(Damp Heat)	* Humidity: 90~95% RH	*Cap change: X7R/X5R: within ±25% Y5V: within ±30%; 6.3V, within +30/-40%
	Steady State	* Test time: 500+24/-0hrs.	*Q/D.F. value:
	, c	* Before initial measurement (Class II only): To apply de-ag	ging X7R/X5R:
		at 150℃ for 1hr then set for 24±2 hrs at room temp.	Rated vol. D.F.
		* Cap. / DF(Q) / I.R. Measurement to be made after de-ag	ng 100V ≤7.5%
		at 150℃ for 1hr then set for 24±2 hrs at room temp.	25V, 16V ≤15%
			10V ≤20%
			50V, 6.3V ≤30%
		1,5	Y5V:
		兴所月	Rated vol. D.F.
		TO A	50V ≤10%
		人人人、传放方	25V ≤15%
		411	16V, 10V ≤20%
		/+////	*I.R.: $1G\Omega$ or $RxC \geqq 10~\Omega$ -F whichever is smaller.
14.	Humidity	* Test temp.: 40±2℃	*No remarkable damage. *Cap change: X7R/X5R: within ±25%
	(Damp Heat)	* Humidity: 90~95%RH	Y5V: within ±30%; 6.3V, within +30/-40%
	Load	* Test time: 500+24/-0 hrs.	A
		* To apply voltage : Rated voltage.	ALI *Q/D.F. value:
		* Before initial measurement (Class II only): To apply de-ag	X7R/X5R:
		at 150℃ for 1hr then set for 24±2 hrs at room temp.	Rated vol. D.F.
		* Cap. / DF(Q) / I.R. Measurement to be made after de-ag	100V ≤7.5%
			25V, 16V ≤15%
		Alca Chalan	10V ≤20%
		at 150°C for 1hr then set for 24±2 hrs at room temp.	50V, 6.3V ≤30% Y5V:
		SCHNULOGY CUD	Rated vol. D.F.
		1.02.001 (01)	
			50V ≤10% 25V ≤15%
			16V, 10V ≤20%
			*I.R.: 500MΩ or RxC≥5 Ω-F whichever is smaller.
15	112	* Test temp. :	
15.	High	NP0, X7R/X7E: 125±3℃	*No remarkable damage. *Cap change: X7R/X5R: within ±25%
	Temperature	X5R, Y5V: 85±3℃	Y5V: within ±30%; 6.3V, within +30/-40%
	Load	* Test time: 1000+24/-0 hrs.	*Q/D.F. value:
	(Endurance)	*To apply voltage: 150% of rated voltage. **100% of rated voltage for below range.	X7R/X5R:
		Pated Canacitanas	Rated vol. D.F.
		Size Dielectric Voltage range	100V ≤7.5%
		TT15 X5R 6.3V C≥1.0μF	25V, 16V ≤15%
		TT18 Y5V 6.3V,10V C≥2.2μF	10V ≤20%
		TT21	50V, 6.3V ≤30%
		TT31 Y5V 6.3V C≥22μF	Y5V:
		*D (Bated vol. D.F.
		*Before initial measurement (Class II only): To apply de-ag at 150°C for 1hr then set for 24±2 hrs at room temp.	ing 50V ≤10%
		* Cap. / DF(Q) / I.R. Measurement to ©r de-aging at 150°C	
		1hr then set for 24±2 hrs at room temp.	16V, 10V ≤20%
			*I.R.: 1GΩ or RxC≧10 Ω-F whichever is smaller.
		.	1011 01 1170 = 10 12 1 WHIGHEVEL 13 3HIGHEL.

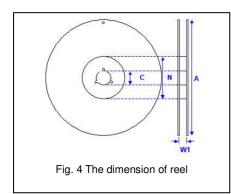
APPENDIXES

■ Tape & reel dimensions





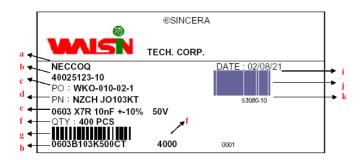
Size	0402	0603	0805	12	06	12	10
Thickness	L	Н	Т	Т	J	Т	К
A ₀	0.70 +/-0.2	1.05 +/-0.30	1.50 +/-0.20	1.90 +/-0.50	< 2.00	< 3.05	< 3.05
B_0	1.20 +/-0.2	1.80 +/-0.30	2.30	3.50 +/-0.50	< 3.70	< 3.80	< 3.80
Т	≤0.80	≦1.20	≦1.30	≦1.30	0.23 +/-0.1	0.23 +/-0.1	0.23 +/-0.1
K ₀	-	+44/17	MAX 3		2.50	< 1.50	< 2.50
W	8.00 +/-0.10	8.00 +/-0.10	8.00 +/-0.10	8.00 +/-0.10	8.00 +/-0.20	8.00 +/-0.20	8.00 +/-0.20
P_0	4.00 +/-0.10						
10xP ₀	40.00 +/-0.10	40.00 +/-0.20	40.00 +/-0.20	40.00 +/-0.20	40.00 +/-0.20	40.00 +/-0.20	40.00 +/-0.20
P ₁	2.00 +/-0.05	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10
P ₂	2.00 +/-0.05						
D_0	1.55 +/-0.05	1.55 +/-0.05	1.55	1.55 +/-0.05	1.50 +0.1/-0	1.50 +0.1/-0	1.50 +0.1/-0
D ₁	-	-	SUNIVULOGY CON	BOKKLIA	1.00 +/-0.10	1.00 +/-0.10	1.00 +/-0.10
E	1.75 +/-0.05	1.75 +/-0.05	1.75 +/-0.05	1.75 +/-0.05	1.75 +/-0.10	1.75 +/-0.10	1.75 +/-0.10
F	3.50 +/-0.05						



Size	0402, 0603, 0805, 1206, 1210						
Reel size	7"	10"	13"				
С	13.0+0.5/-0.2	13.0+0.5/-0.2	13.0+0.5/-0.2				
W ₁	8.4+1.5/-0	8.4+1.5/-0	8.4+1.5/-0				
Α	178.0±1.0	250.0±1.0	330.0±1.0				
N	60.0+1.0/-0	100.0±1.0	100±1.0				



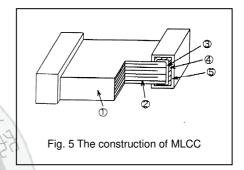
Description of customer label



- a. Customer name
- b. WTC order series and item number
- c. Customer P/O
- d. Customer P/N
- e. Description of product
- f. Quantity
- g. Bar code including quantity & WTC P/N or customer
- h. WTC P/N
- i. Shipping date
- j. Order bar code including series and item numbers
- k. Serial number of label

Constructions

No.	Nam	пе	X7R, X5R, Y5V			
①	Ceramic r	material	BaTiO₃ based			
2	Inner ele	ctrode	Ni.			
3		Inner layer	Cu			
4	Termination	Middle layer	以 A No No No No			
(5)		Outer layer	Sn (Matt)			





Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

■ Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N_2 within oven are recommended.

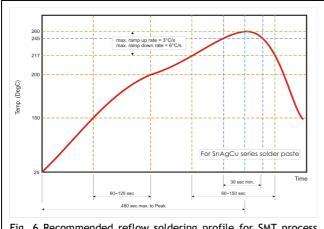


Fig. 6 Recommended reflow soldering profile for SMT process with SnAgCu series solder paste.

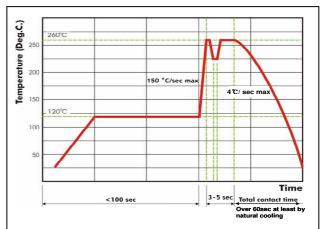


Fig. 7 Recommended wave soldering profile for SMT process with ${\sf SnAgCu}$ series solder.

